claims 1 or 2, wherein only said first and second strip lines are placed on said dielectric sheet.

9. (Amended) The laminated bandpass filter according to any one of claims 1, 2, 6 or 7, further comprising:

a third capacitor electrode connected to said input electrode;

a fourth capacitor electrode connected to said output electrode;

a fifth capacitor electrode capacitatively coupled with said third capacitor electrode; and

a sixth capacitor electrode capacitatively coupled with said fourth capacitor electrode,

wherein capacitative coupling of an area where said third capacitor electrode and said sixth capacitor electrode overlap each other in the lamination direction forms a jump capacitance.

10. (Amended) The laminated bandpass filter according to any one of claims 1, 2, 6 or 7, wherein capacitative coupling of an area where said fourth capacitor electrode and said fifth capacitor electrode overlap each other in the lamination direction forms a jump capacitance.

11. (Twice Amended) The laminated bandpass filter according to any one of claims 1, 2, 6 or 7, wherein with respect to said internal grounding electrode, on a layer superior thereto, an electrode pattern of at least one of said first and second capacitor electrodes is laminated, an electrode pattern of at least one of said first and second strip lines is laminated on a layer superior thereto, and an electrode pattern of at least one of the

capacitor electrode connected to said input electrode and the capacitor electrode connected to said output electrode is laminated on a layer superior to said layer.

12. (Twice Amended) The laminated bandpass filter according to any one of claims 1, 2, 6 or 7, wherein all electrode patterns constituting the capacitor electrode connected to said input electrode, the capacitor electrode connected to said output electrode and an input/output capacitance are provided on a layer superior to the layer constituting said strip lines.

13. (Twice Amended) The laminated bandpass filter according to claim 9, wherein with respect to said internal grounding electrode, on a layer superior thereto, an electrode pattern of at least one of said first and second capacitor electrodes is laminated, an electrode pattern of at least one of said first and second strip lines is laminated on a layer superior thereto, and an electrode pattern of at least one of said third to sixth capacitor electrodes is laminated on a layer superior to said layer.

A34 Sub

14. (Twice Amended) The laminated bandpass filter according to claim 9, wherein said all of third to sixth capacitor electrodes are provided on a layer superior to the layer constituting said strip lines.

---

18. (Amended) The laminated bandpass filter according to claims 15 or 16, wherein said first to fourth strip lines are connected to said internal grounding electrode via a via hole.

A35

19. (Twice Amended) The laminated bandpass filter according to claims 15 or 16, further comprising:

a fifth capacitor electrode connected to said input electrode;

a sixth capacitor electrode connected to said output electrode;

a seventh capacitor electrode capacitatively coupled with said fifth capacitor electrode; and

an eighth capacitor electrode capacitatively coupled with said sixth capacitor electrode,

wherein capacitative coupling of an area where said fifth capacitor electrode and said eighth capacitor electrode overlap each other in the lamination direction forms a jump capacitance.

20. (Amended) The laminated bandpass filter according to claims 15 or 16, wherein capacitative coupling of an area where said sixth capacitor electrode and said seventh capacitor electrode overlap each other in the lamination direction forms a jump capacitance.

Claim 21 has been cancelled.

22. (Twice Amended) A composite high frequency device, wherein said laminated body incorporates the bandpass filter according to any one of claims 1, 2, 6, 7, 15 or 16 and another high frequency circuit.

23. (Twice Amended) A composite high frequency device, wherein electronic parts are mounted on said laminated body incorporating the bandpass filter according to any one of claims 1, 2, 6, 7, 15 or 16.

24. (Twice Amended) The laminated bandpass filter according to any one of claims 1, 2, 6, 7, 15 or 16, wherein said dielectric sheet

is made up of a crystal phase and a glass phase, said crystal phase includes at least one of Al_2O_3, MgO, SiO_3 and RO_a where R is at least one element selected from La, Ce, Pr, Nd, Sm and Gd and a is a numerical value determined stoichiometrically according to the valence of said R.

25. (Amended) A high frequency device, characterized by comprising the laminated bandpass filter according to any one of claims 1, 2, 6, 7, 15 or 16.

Respectfully submitted,

Allan Ratner, Reg. No. 19,717
Attorney for Applicants

AR/dlm
Enclosure: Version With Markings Showing Changes Made

Dated: March 25, 2002

Suite 301, One Westlakes, Berwyn
P.O. Box 980
Valley Forge, PA 19482-0980
(610) 407-0700

The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. **18-0350** of any fees associated with this communication.

EXPRESS MAIL Mailing Label Number: EV 029154666 US
Date of Deposit: March 25, 2002

I hereby certify that this paper and fee are being deposited, under 37 C.F.R. § 1.10 and with sufficient postage, using the "Express Mail Post Office to Addressee" service of the United States Postal Service on the date indicated above and that the deposit is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Kathleen Libby